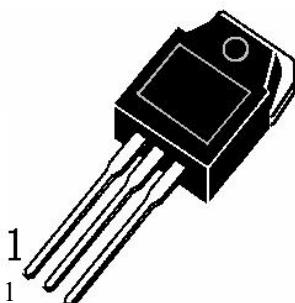


### ◆ Features:

- ◊ Fast switching speed  
开关速度快
- ◊ High input impedance and low level drive  
高输入阻抗和低电平驱动
- ◊ Avalanche energy tested  
雪崩能量测试
- ◊ Improved dv/dt capability, high ruggedness  
提高 dv/dt 能力，高耐用性

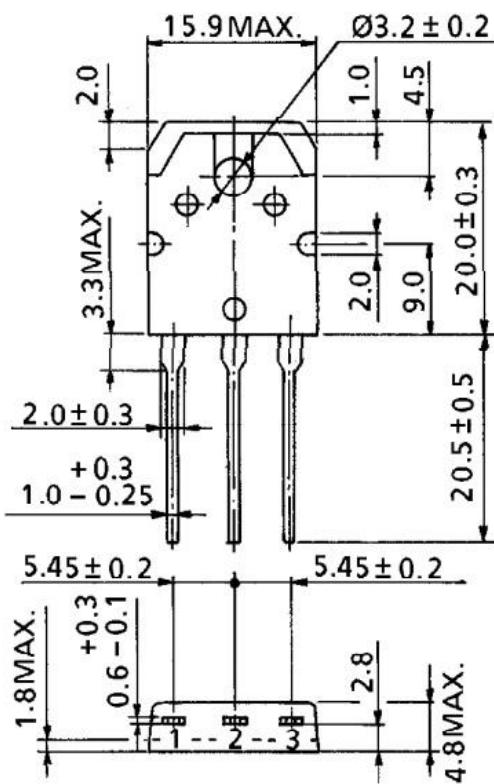
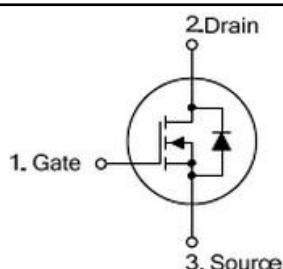
RoHS  
COMPLIANT

TO-3PN



### ◆ Applications

- ◊ High efficiency switch mode power supplies  
高效率开关电源
- ◊ Power factor correction  
功率因数校正
- ◊ Electronic lamp ballast  
电子整流器





**OSH10N80**  
**800V N-CHANNEL MOSFET**

◆ **Absolute Maximum Ratings (Tc=25°C)**

Symbol	Parameters	Ratings	Unit
V <sub>DSS</sub>	Drain-Source Voltage 漏源电压	800	V
V <sub>GS</sub>	Gate-Source Voltage-Continuous 栅源电压	±30	V
I <sub>D</sub>	Drain Current-Continuous (Note 2) 漏极持续电流	10	A
I <sub>DM</sub>	Drain Current-Single Plused (Note 1) 漏极单次脉冲电流	40	A
P <sub>D</sub>	Power Dissipation (Note 2) 功率损耗	240	W
T <sub>j</sub>	Max.Operating junction temperature 最大结温	150	°C

◆ **Electrical characteristics (Tc=25°C unless otherwise noted)**

Symbol	Parameters	Min	Typ	Max	Units	Conditions
<b>Static Characteristics</b>						
B <sub>VDSS</sub>	Drain-Source Breakdown VoltageCurrent (Note 1) 漏极击穿电压	800	--	--	mA	I <sub>D</sub> =250μA, V <sub>GS</sub> =0V, T <sub>j</sub> =25°C
V <sub>GS(th)</sub>	Gate Threshold Voltage 栅极开启电压	3.0	--	5.0	V	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA
R <sub>DS(on)</sub>	Drain-Source On-Resistance 漏源导通电阻	--	0.88	1.2	Ω	V <sub>GS</sub> =10V, I <sub>D</sub> =5A
I <sub>GSS</sub>	Gate-Body Leakage Current 栅极漏电流	--	--	±100	nA	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0
I <sub>DSS</sub>	Zero Gate Voltage Drain Current 零栅极电压漏极电流	--	--	1	μA	V <sub>DS</sub> =800V, V <sub>GS</sub> =0



OSH10N80

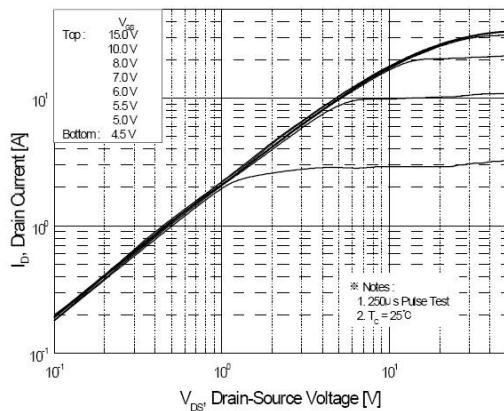
800V N-CHANNEL MOSFET

Switching Characteristics						
$T_{d(on)}$	Turn-On Delay Time 开启延迟时间	--	<b>50</b>	<b>110</b>	ns	$V_{DS}=400V, I_D=10A,$ $R_G=25\Omega$ (Note 2)
$T_r$	Rise Time 上升时间	--	<b>130</b>	<b>270</b>	ns	
$T_{d(off)}$	Turn-Off Delay Time 关闭延迟时间	--	<b>90</b>	<b>190</b>	ns	
$T_f$	Fall Time 下降时间	--	<b>80</b>	<b>165</b>	ns	
$Q_g$	Total Gate Charge 栅极总电荷	--	<b>45</b>	<b>58</b>	nC	
$Q_{gs}$	Gate-Source Charge 栅源极电荷	--	<b>13.5</b>	--	nC	
$Q_{gd}$	Gate-Drain Charge 栅漏极电荷	--	<b>17</b>	--	nC	
Dynamic Characteristics						
$C_{iss}$	Input Capacitance 输入电容	--	<b>2150</b>	<b>2800</b>	pF	$V_{DS}=25V, V_{GS}=0,$ $f=1MHz$
$C_{oss}$	Output Capacitance 输出电容	--	<b>180</b>	<b>230</b>	pF	
$C_{rss}$	Reverse Transfer Capacitance 反向传输电容	--	<b>15</b>	<b>20</b>	pF	
$I_s$	Continuous Drain-Source Diode Forward Current (Note 2) 二极管导通正向持续电流	--	--	<b>10</b>	A	
$V_{SD}$	Diode Forward On-Voltage 二极管正向导通电压	--	--	<b>1.4</b>	V	$I_s=10A, V_{GS}=0$
$R_{th(j-c)}$	Thermal Resistance, Junction to Case 结到外壳的热阻	--	--	<b>2.6</b>	°C/W	

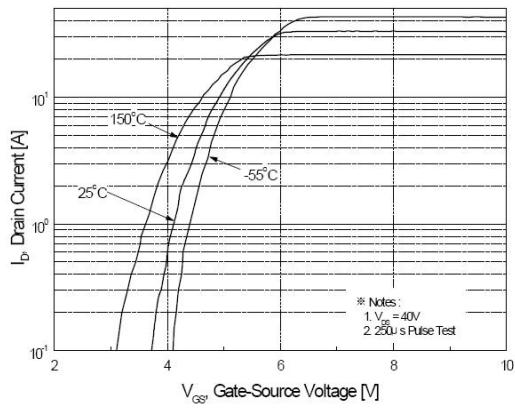
Note 1: Repetitive Rating : Pulse width limited by maximum junction temperature

Note 2: Pulse test: PW &lt;= 300us , duty cycle &lt;= 2%.

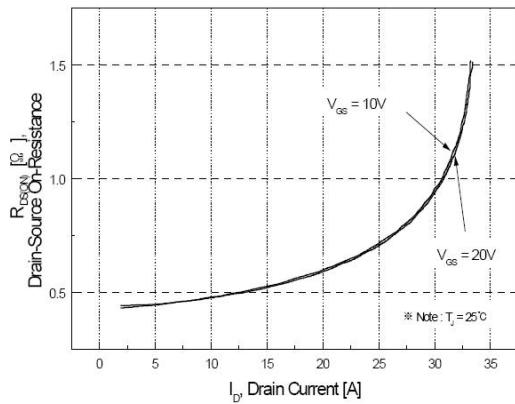
## ◆ Ratings and Characteristic curves



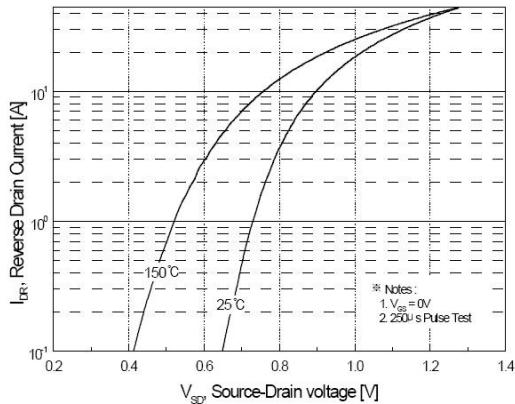
**Figure 1. On-Region Characteristics**



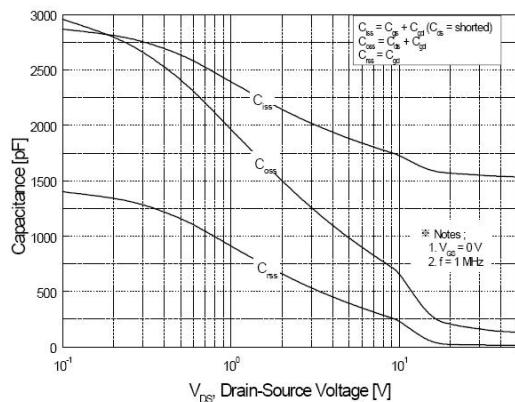
**Figure 2. Transfer Characteristics**



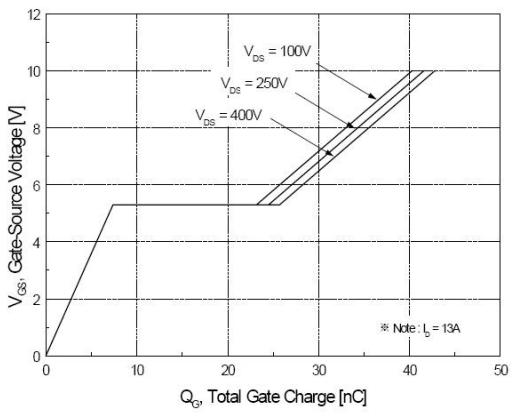
**Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage**



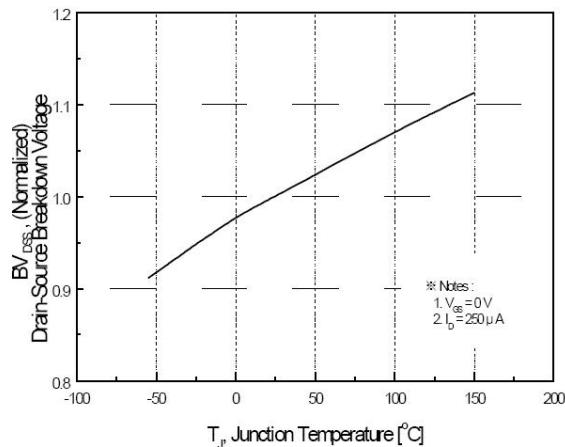
**Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature**



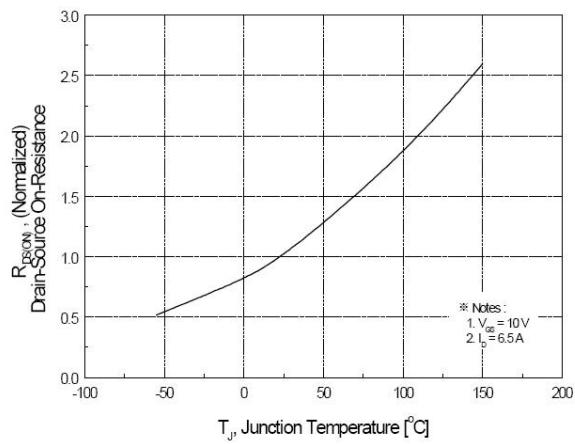
**Figure 5. Capacitance Characteristics**



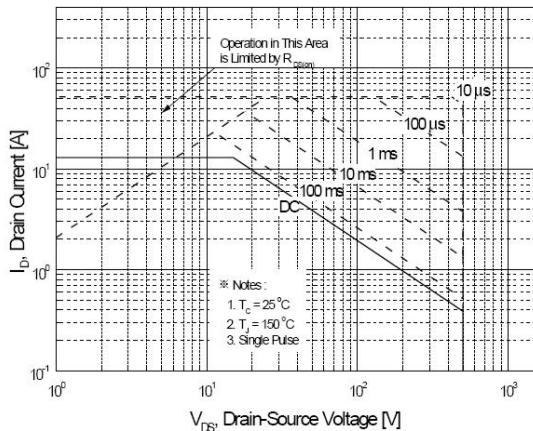
**Figure 6. Gate Charge Characteristics**



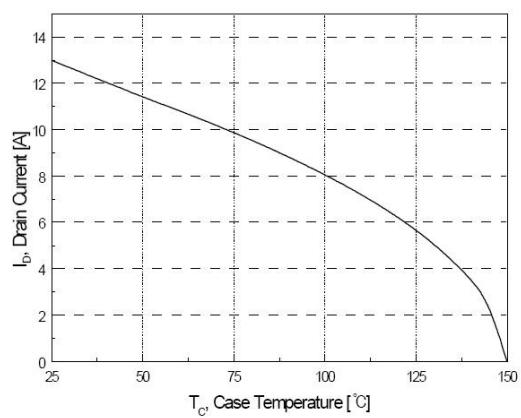
**Figure 7. Breakdown Voltage Variation  
vs Temperature**



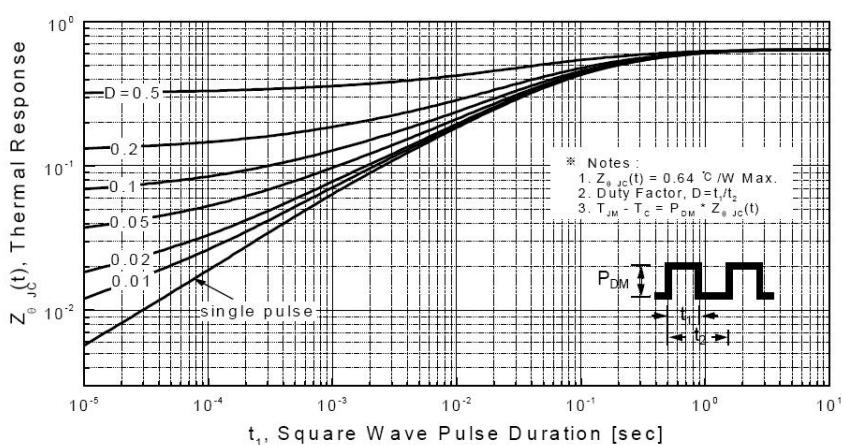
**Figure 8. On-Resistance Variation  
vs Temperature**



**Figure 9. Maximum Safe Operating Area**



**Figure 10. Maximum Drain Current  
vs Case Temperature**



**Figure 11. Transient Thermal Response Curve**

Fig 12. Gate Charge Test Circuit & Waveform

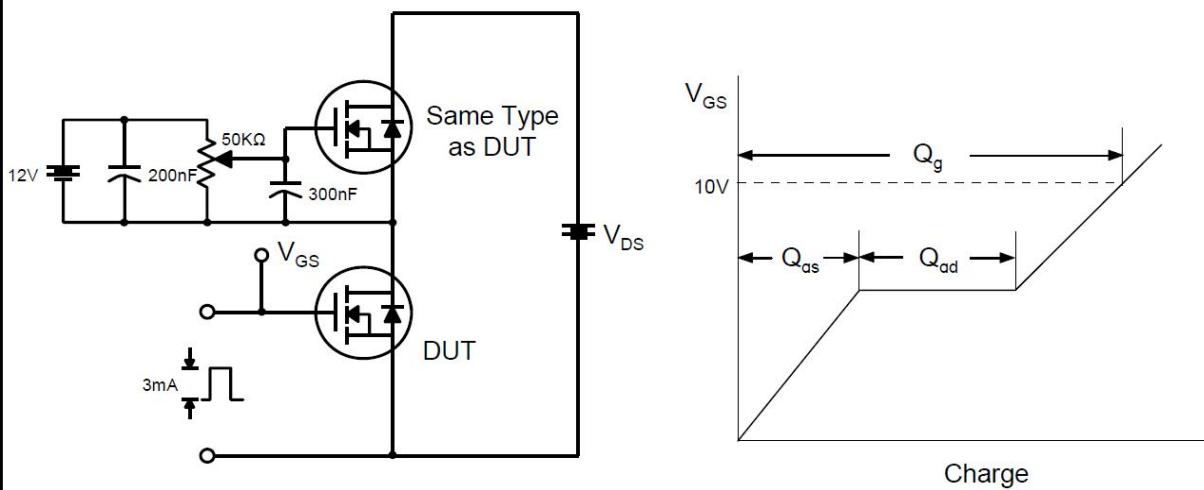


Fig 13. Resistive Switching Test Circuit & Waveforms

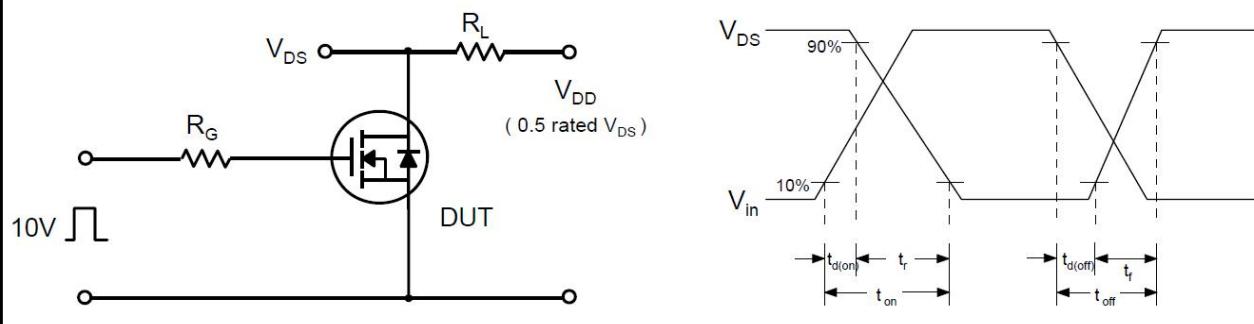


Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms

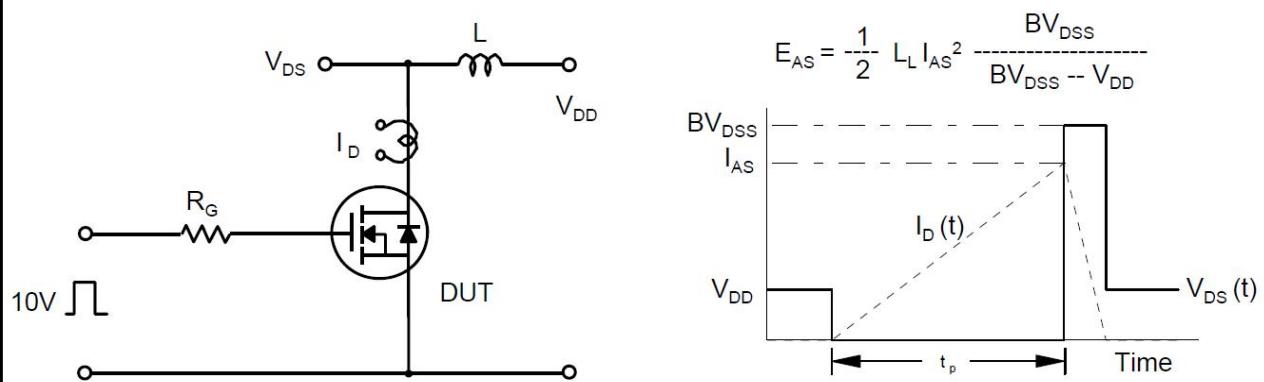


Fig 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

